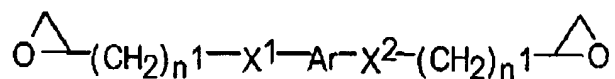


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### AMENDMENTS TO THE CLAIMS

1. (Original) A compound comprising:  
  
at least one epoxy group;  
  
a melting point temperature that is less than 140°C; and  
  
liquid crystallinity at a temperature greater than 150°C.
2. (Original) A composition comprising:  
  
the compound of claim 1; and  
  
a filler having a coefficient of thermal expansion that is comparable to that of silicon.
3. (Withdrawn) A method comprising:  
  
contacting a surface of a microelectronic device with the composition of claim 2;  
  
and  
  
solidifying the composition on the surface.
4. (Withdrawn) A microelectronic device comprising:  
  
a surface; and  
  
a composition solidified on the surface by the method of claim 3.
5. (Original) The compound of claim 1, having the formula:



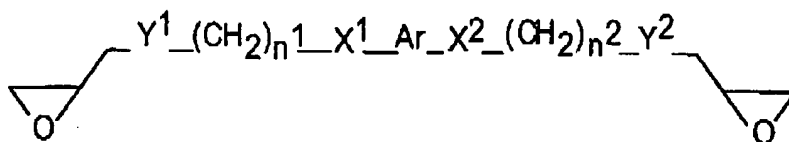
wherein

Ar includes a liquid crystalline moiety selected from trans-stilbenediyl, triphenyl, 1,4-bis(phenoxy carbonyl)cyclohexdiyl, and diphenyl 1,4-cyclohexane-dicarboxylate;

X<sup>1</sup> and X<sup>2</sup> independently of one another are selected from oxygen, carbonyl, carboxyl, oxycarbonyl, and amine; and

n<sup>1</sup> and n<sup>2</sup> independently of one another are numbers selected from 4 to 6.

6. (Original) The compound of claim 1, having the formula:



wherein

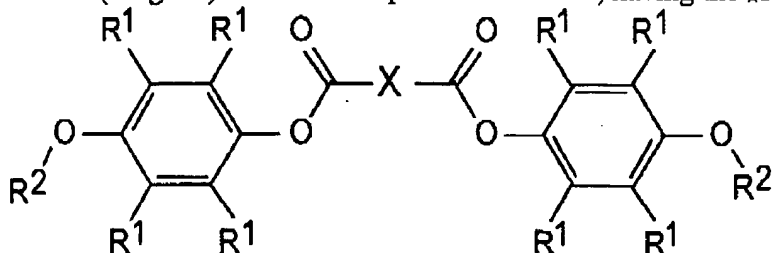
Ar includes a liquid crystalline moiety selected from trans-stilbenediyl, triphenyl, 1,4-bis(phenoxy carbonyl)cyclohexdiyl, diphenyl 1,4-cyclohexanedicarboxylate;

X<sup>1</sup> and X<sup>2</sup> independently of one another are selected from oxygen, carbonyl, carboxyl, oxycarbonyl, and amine;

Y<sup>1</sup> and Y<sup>2</sup> independently of one another are selected from oxygen, carbonyl, carboxyl, oxycarbonyl, and amine; and

n<sup>1</sup> and n<sup>2</sup> independently of one another are numbers selected from 4 to 6.

7. (Original) The compound of claim 1, having the formula:



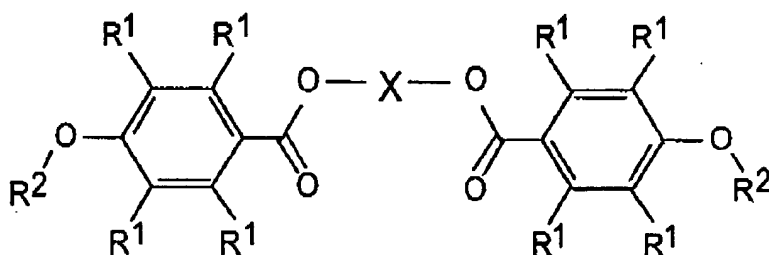
wherein

X is selected from a C<sub>6-10</sub> aryl group and a C<sub>5-10</sub> alicyclic group;

each R<sup>1</sup> is independently selected from hydrogen, halogen, and C<sub>1-3</sub> alkyl optionally substituted with halogen, provided that not more than four of the R<sup>1</sup> are C<sub>2</sub> alkyl optionally substituted with halogen, and provided that not more than three of the R<sup>1</sup> are C<sub>3</sub> alkyl optionally substituted with halogen; and

each R<sup>2</sup> is independently selected from a C<sub>2-6</sub> epoxy.

8. (Original) The compound of claim 1, having the formula:



wherein

X is selected from a C<sub>6-10</sub> aryl group and a C<sub>5-10</sub> alicyclic group;

each R<sup>1</sup> is independently selected from hydrogen, halogen, and C<sub>1-3</sub> alkyl optionally substituted with halogen, provided that not more than four of the R<sup>1</sup> are

C<sub>2</sub> alkyl optionally substituted with halogen, and provided that not more than three of the R<sup>1</sup> are C<sub>3</sub> alkyl optionally substituted with halogen;

each R<sup>2</sup> is independently selected from a C<sub>2-6</sub> epoxy.

9. – 48. (Cancelled)

49. (New) The composition of claim 2, wherein the coefficient of thermal expansion of the filler is matched to that of silicon.

50. (New) The composition of claim 2, wherein the filler comprises one or more selected from silicon particles, silica particles, sand, quartz, silicon dioxide, and clay.

51. (New) The composition of claim 2, wherein a weight percent of the filler in the composition ranges from 50 to 95 wt%.

52. (New) The composition of claim 2, wherein the composition comprises an epoxy molding composition.

53. (New) The composition of claim 2, further comprising:

a curing agent;

a curing accelerator; and

a curing inhibitor.